



Features

- High speed 10MBit/s
- High isolation voltage between input and output (Viso=3750 Vrms)
- Guaranteed performance from -40°C to 85°C
- Wide operating temperature range of -55°C to 125°C
- Halogen free Package
- Regulatory Approvals
 - UL - UL1577 (E364000)
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC – GB4943.1, GB8898
 - IEC60065, IEC60950

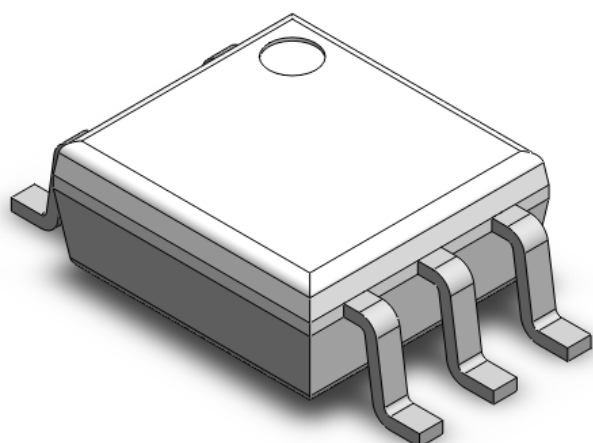
Description

The CTM410 optocouplers consist of an AlGaAs LED and high-speed photodetector with a strobable output. The switching parameters are guaranteed over the temperature range of -40°C to +85°C. A maximum input signal of 10mA will provide a minimum output sink current of 13mA (fan out of 8).

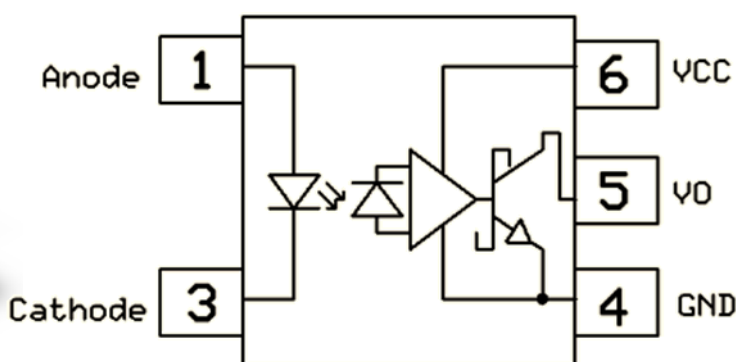
Applications

- Line receivers
- Telecommunication equipment
- High speed logic ground isolation
- Feedback loop in switch-mode power supplies
- Home appliances

Package Outline



Schematic



Note: Different bending options available. See package dimension.

**Absolute Maximum Rating at 25°C**

<i>Symbol</i>	<i>Parameters</i>	<i>Ratings</i>	<i>Units</i>	<i>Notes</i>
V _{ISO}	Isolation voltage	3750	V _{RMS}	1
T _{OPR}	Operating temperature	-55 ~ + 125	°C	
T _{STG}	Storage temperature	-55 ~ +150	°C	
T _{SOL}	Soldering temperature	260	°C	2
Emitter				
I _F	Forward current	50	mA	
V _R	Reverse voltage	5	V	
P _D	Power dissipation	100	mW	
Detector				
P _D	Power dissipation	85	mW	
I _O	Average Output current	50	mA	
V _{CC}	Supply voltage	7	V	
V _O	Output voltage	7	V	

Notes

1. AC for 1 minute, RH = 40 ~ 60%.
2. For 10 second peak



Electrical Characteristics

Over recommended temperature ($T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$) unless otherwise specified. All Typical at $T_A = 25^{\circ}\text{C}$.

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	$I_F = 10\text{mA}$	-	1.6	1.8	V	
V_R	Reverse Voltage	$I_R = 5\mu\text{A}$	5.0	-	-	V	
$\Delta V_F / \Delta T_A$	Temperature coefficient of forward voltage	$I_F = 10\text{mA}$	-	-1.6	-	mV/ $^{\circ}\text{C}$	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I_{CCL}	Logic Low Supply Current	$I_F = 10\text{mA}$, $V_O = \text{Open}$, $V_{CC} = 5\text{V}$	-	9	13	mA	
I_{CCH}	Logic High Supply Current	$I_F = 0\text{mA}$, $V_O = \text{Open}$, $V_{CC} = 5\text{V}$	-	6	10	mA	
R_{IO}	Isolation Resistance	$V_{IO} = 500\text{V}_{DC}$	5×10^{10}	-	-	Ω	
C_{IO}	Isolation Capacitance	$f = 1\text{MHz}$	-	0.5	1.2	pF	

Transfer Characteristics

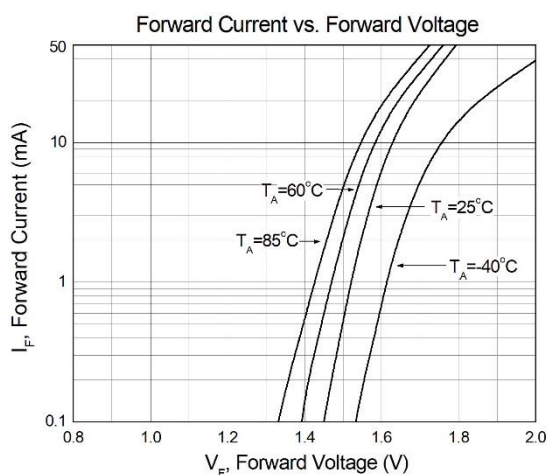
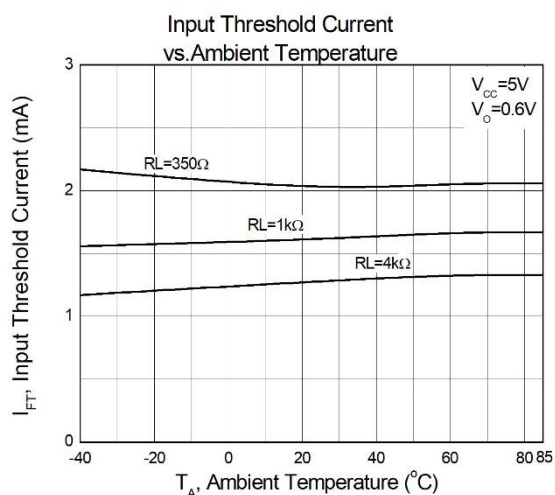
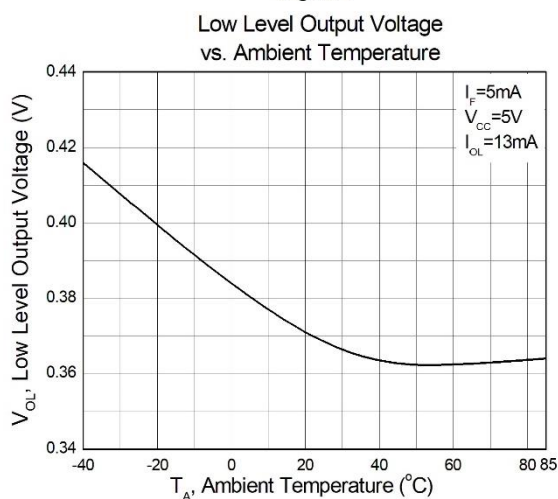
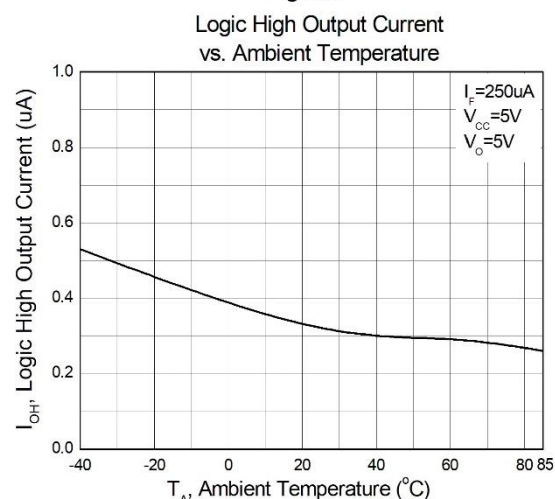
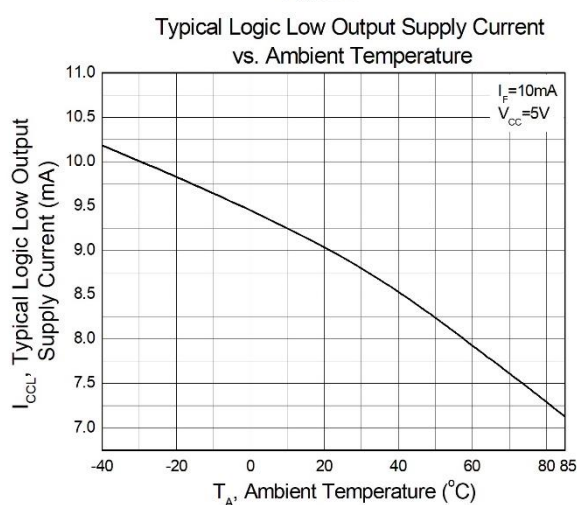
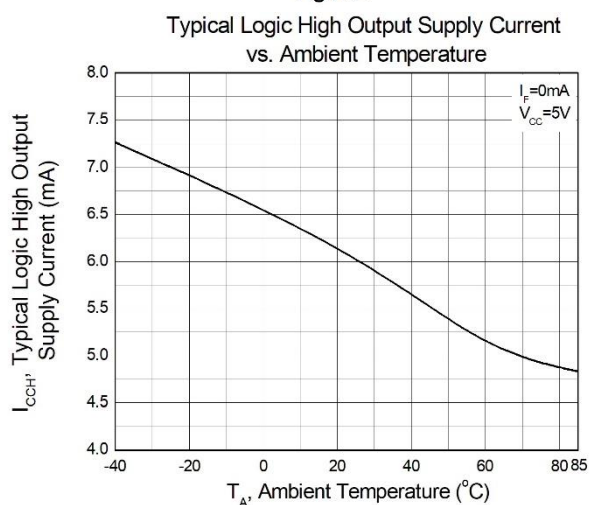
Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I_{OH}	Logic High Output Current	$I_F = 250\mu\text{A}$, $V_O = 5.5\text{V}$,		2	100	μA	
I_{FT}	Input Threshold Current	$V_{CC} = 5.5\text{V}$, $V_O = 0.6\text{V}$, $I_O = 13\text{mA}$	-	2	5	mA	
V_{OL}	Logic Low Output Voltage	$I_F = 5\text{mA}$, $I_O = 13\text{mA}$, $V_{CC} = 5.5\text{V}$	-	0.35	0.6	V	

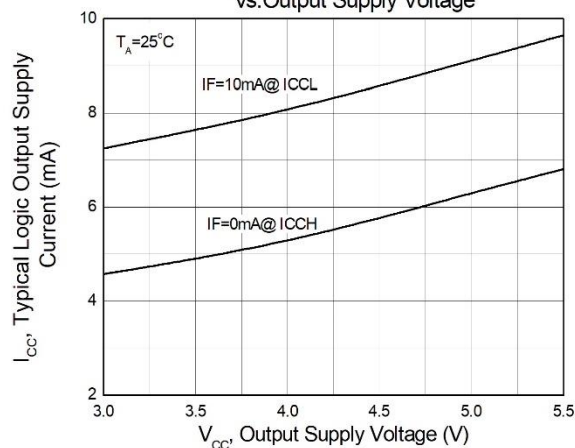
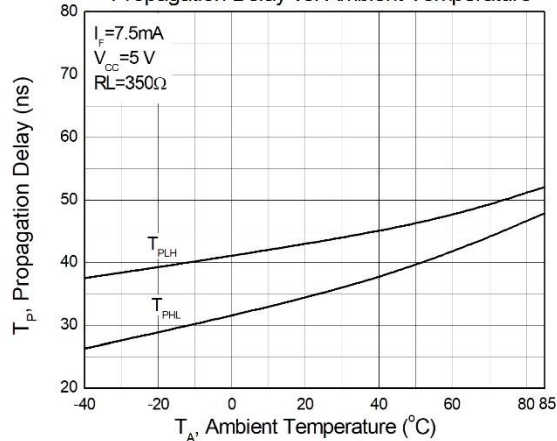
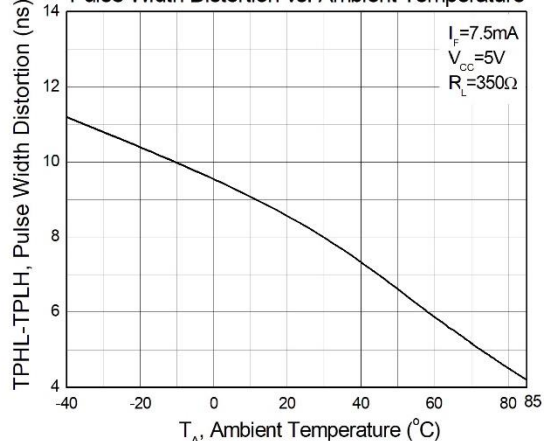
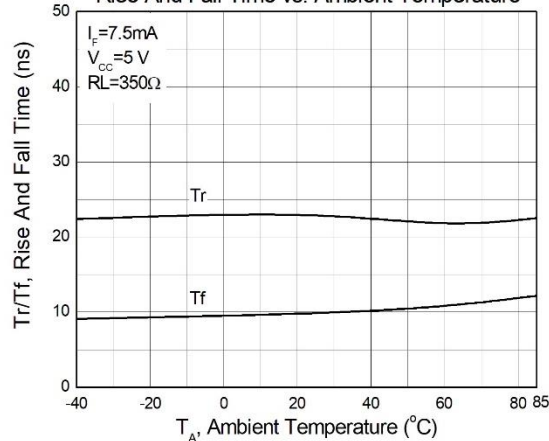
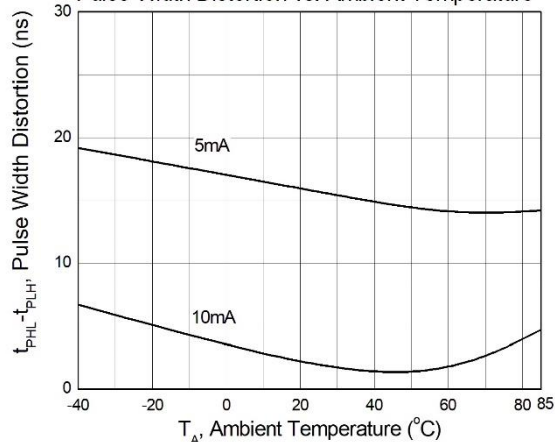
**Switching Characteristics**

<i>Symbol</i>	<i>Parameters</i>	<i>Test Conditions</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Units</i>	<i>Notes</i>
T_{PHL}	Propagation Delay Time Logic High to Logic Low	$C_L=15pF, R_L=350\Omega$	-	40	75	ns	
T_{PLH}	Propagation Delay Time Logic Low to Logic High		-	35	75	ns	
T_r	Output Rise Time		-	40	-	ns	
T_f	Output Fall Time		-	10	-	ns	
CM_H	Common Mode Transient Immunity at Logic High	$I_F = 0mA$, $V_{OH}=2.0V$, $R_L=350\Omega$, $T_A=25^\circ C$, $V_{CM}=1000Vp-p$	10000	-	-	V/ μs	
CM_L	Common Mode Transient Immunity at Logic Low	$I_F = 7.5mA$, $V_{OL}=0.8V$, $R_L=350\Omega$, $T_A=25^\circ C$, $V_{CM}=1000Vp-p$	10000	-	-	V/ μs	



Typical Characteristic Curves

**Figure 1****Figure 2****Figure 3****Figure 4****Figure 5****Figure 6**

**10Mbit/s 5-Pin Mini-Flat Logic Gate Optocoupler****Typical Logic Output Supply Current
vs. Output Supply Voltage****Figure 7****Propagation Delay vs. Ambient Temperature****Figure 8****Pulse Width Distortion vs. Ambient Temperature****Figure 9****Rise And Fall Time vs. Ambient Temperature****Figure 10****Pulse Width Distortion vs. Ambient Temperature****Figure 11**



Test Circuits

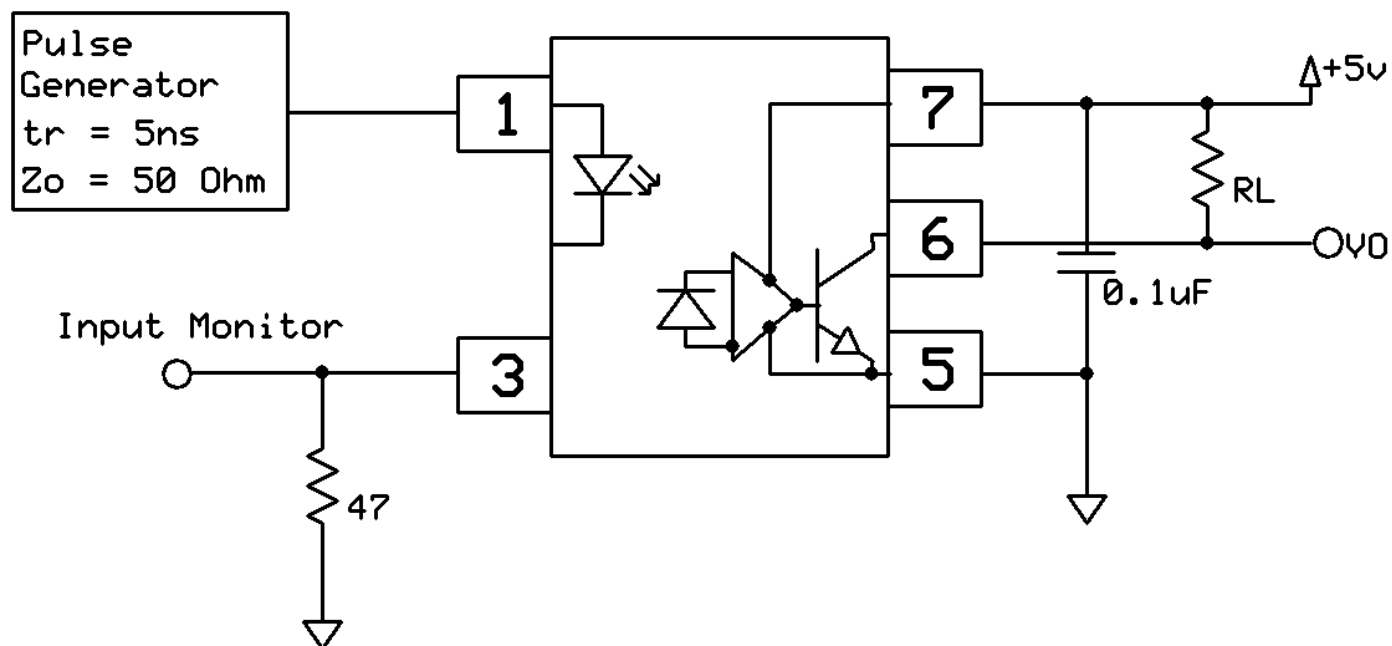


Figure 12

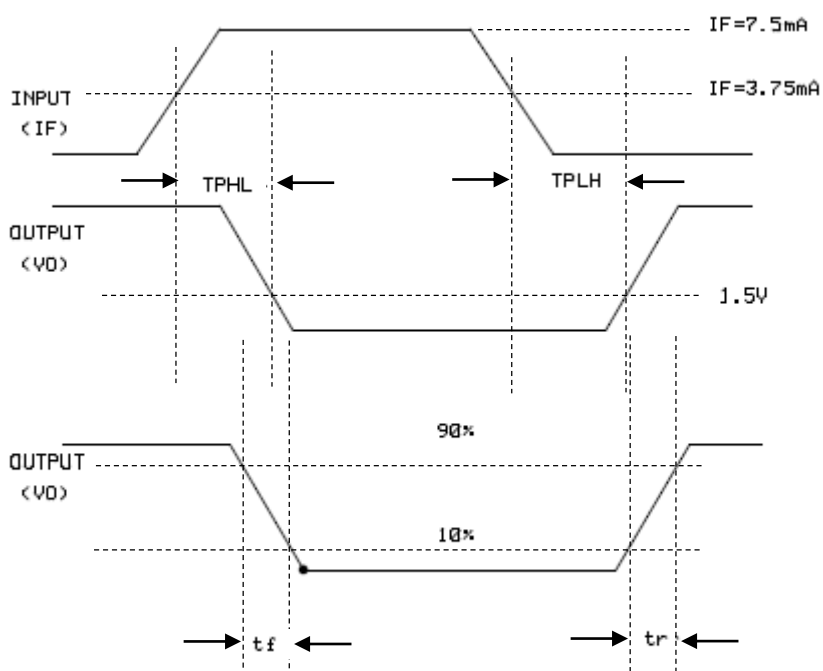
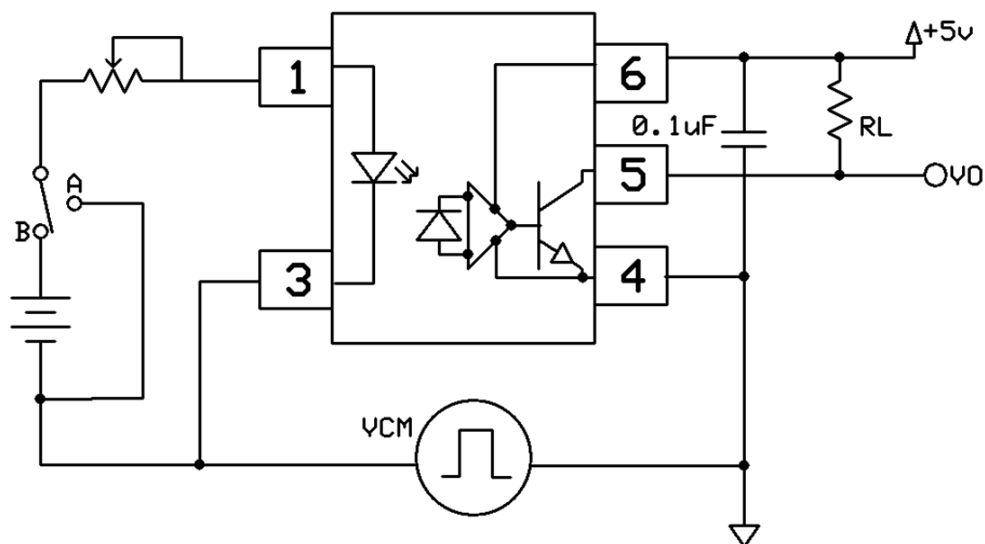
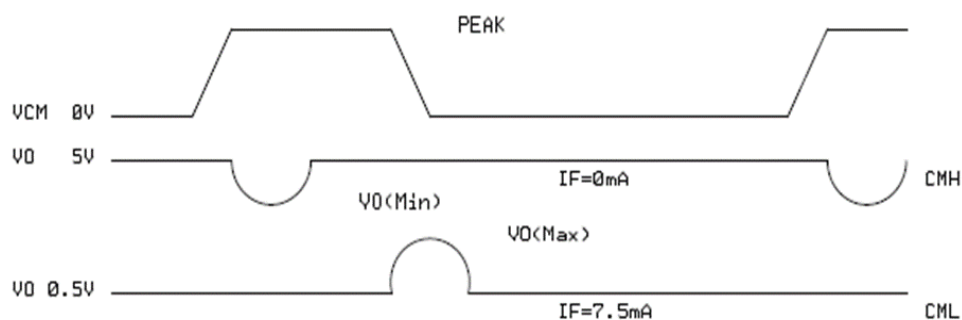
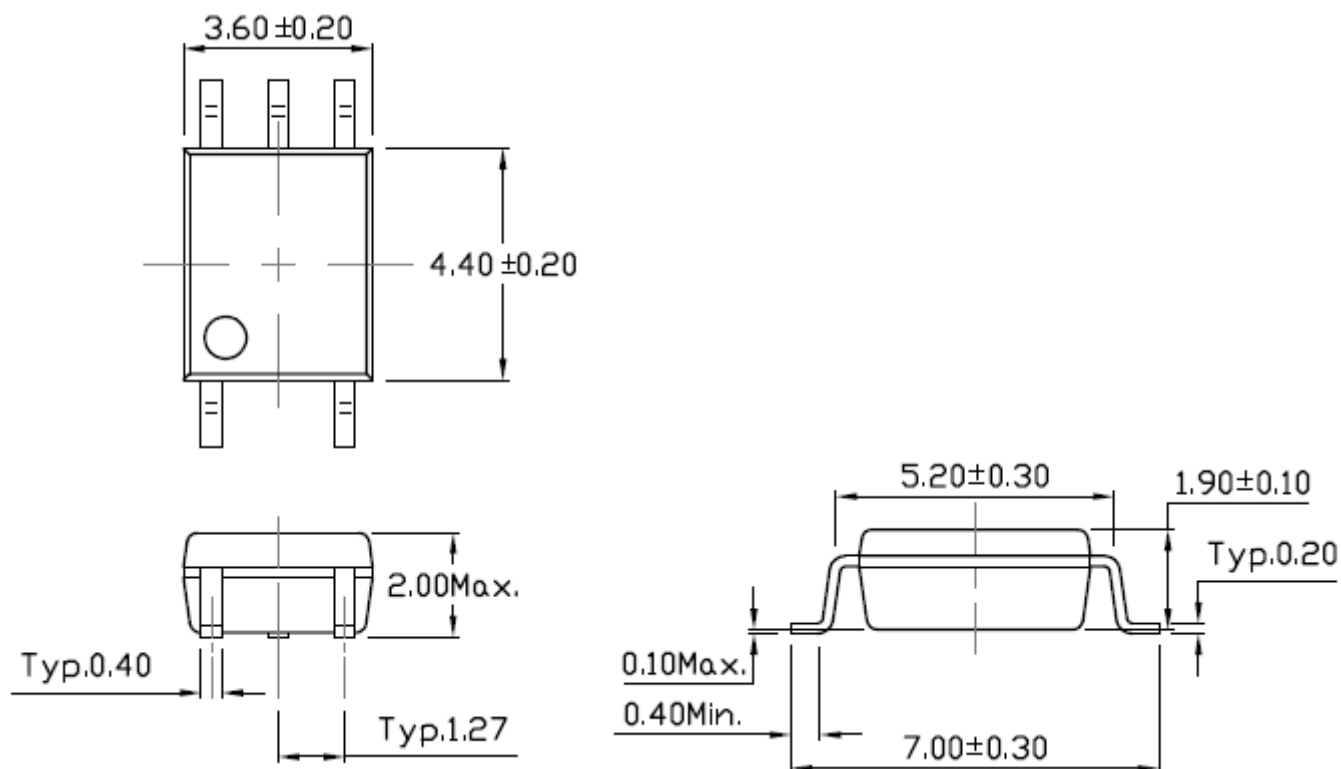
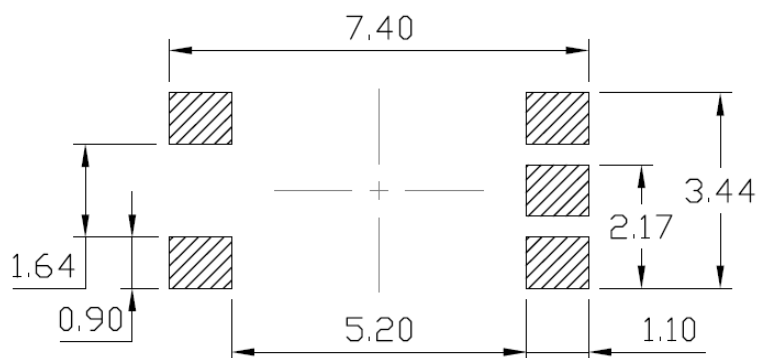


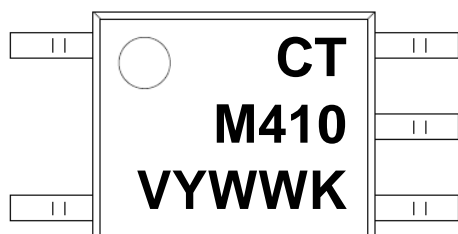
Figure 13

**Test Circuits****Figure 14****CMR Test Circuit****Figure 15**

**Package Dimension** *Dimensions in mm unless otherwise stated***Recommended Solder Mask** *Dimensions in mm unless otherwise stated*



Device Marking

**Note:**

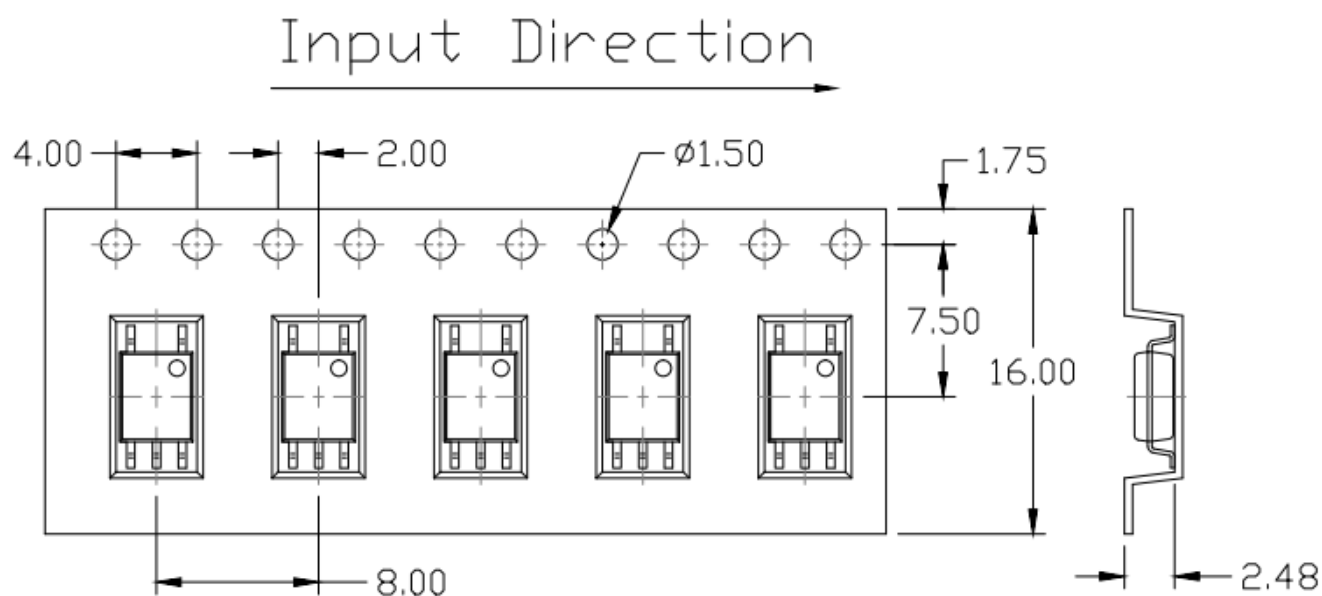
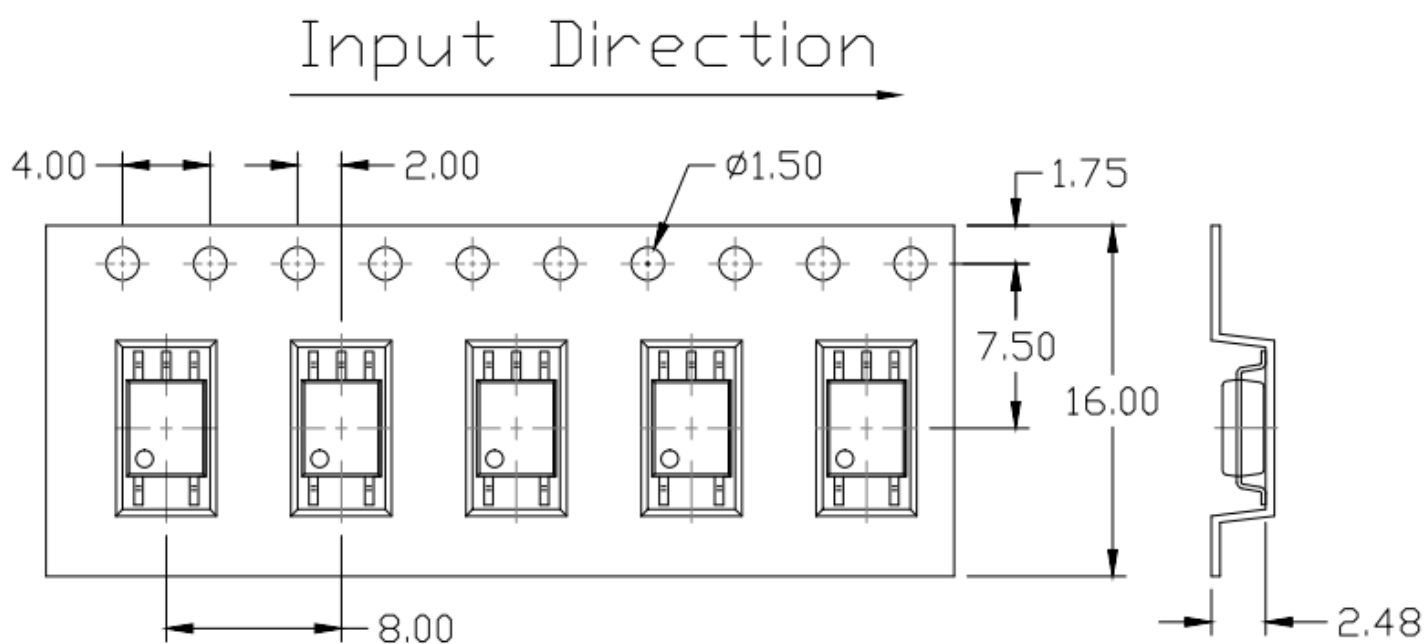
CT : Denotes “CT Micro”
M410 : Product Number
V : VDE Option (V or none)
Y : Fiscal Year
WW : Work Week
K : Production Code

Ordering Information

CTM410(V)(Y)

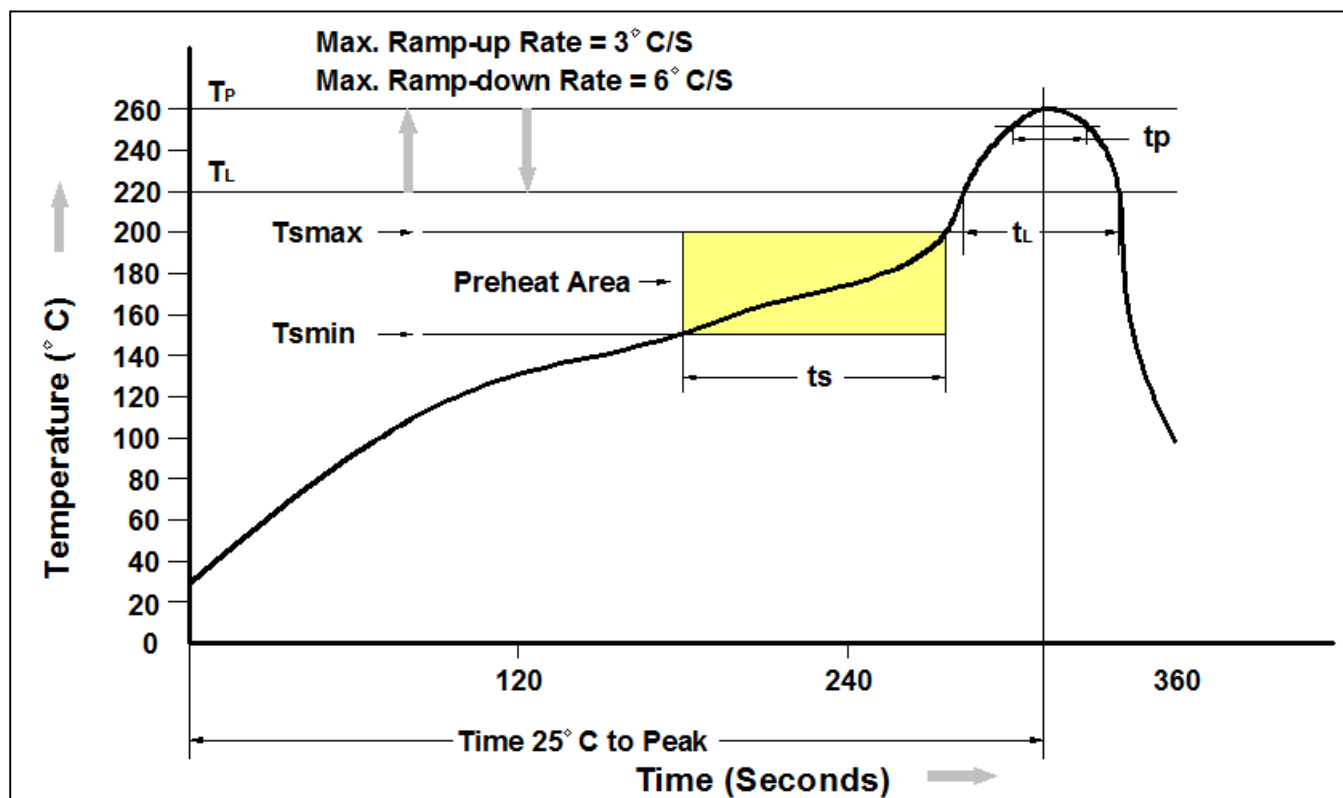
CT : Denotes “CT Micro”
M410 : Part Number
V : VDE Safety Option (V or none)
Y : Tape and reel option (T1 or T2)

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Taping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	3000 Units/Reel

**Carrier Tape Specifications** *Dimensions in mm unless otherwise stated***Option T1****Option T2**



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

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